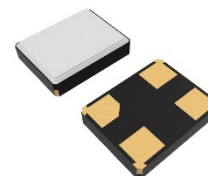


Description

The ABM8N series is an AT-Cut MHz quartz crystal offered in a 3.2mm x 2.5mm x 0.8mm four-pad SMD package. Tight frequency accuracy of $\pm 10\text{ppm}$ and stability of $\pm 15\text{ppm}$ over operating temperature range of -40°C to $+85^{\circ}\text{C}$, low plating load (CL) value of 4pF, and low Equivalent Series Resistance (ESR) is achieved in this compact package. The ABM8N series offers industry standard frequencies common for wearables, IoT, Bluetooth / Bluetooth Low Energy (BLE), and Ultra-Low Power MCU's/SoC's/Transceivers end applications.



Features

- Optimized for energy saving wearables and IoT applications
- Plated at exceptionally low plating capacitance, as low as 4pF, with optimized ESR
- Seam sealed for long-term reliability
- [REACH/RoHS II Compliant](#) | [MSL Level N/A](#)

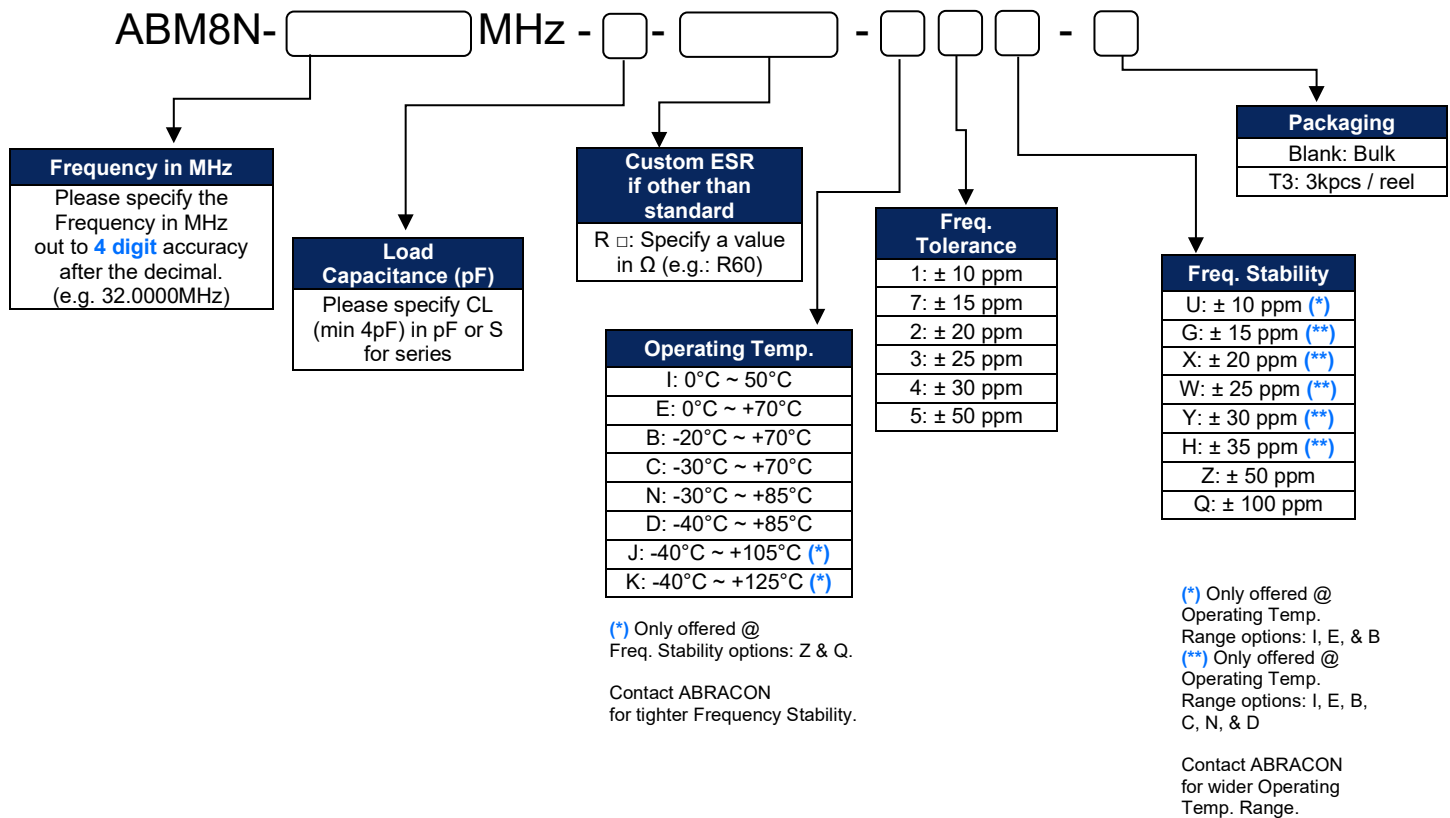
Typical Applications

- Wearables
- Wireless Modules
- Internet of Things (IoT)
- Bluetooth / Bluetooth Low Energy (BLE)
- Machine-to-Machine (M2M) Connectivity
- Ultra-Low Power MCU's, SoC's, Transceivers
- Near Field Communication
- ISM Band Applications

Electrical Specifications

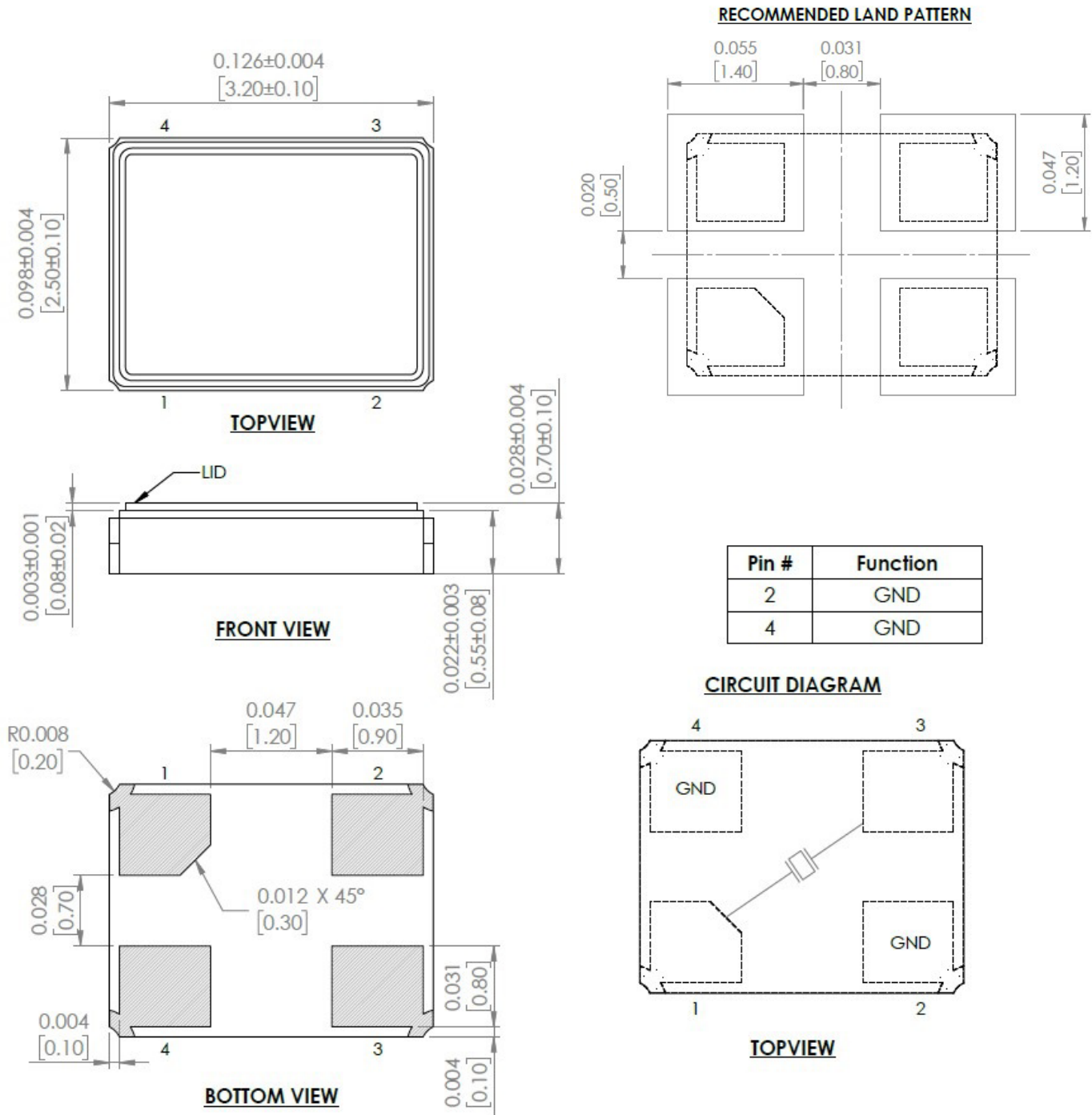
Parameters	Min.	Typ.	Max.	Units	Notes
Frequency Range	10.0000		54.0000	MHz	
Operation Mode	Fundamental				
Operating Temperature Range	-40		+125	$^{\circ}\text{C}$	See options
Storage Temperature	-55		+125	$^{\circ}\text{C}$	
Frequency Tolerance @ $+25^{\circ}\text{C}$	-10		+10	ppm	See options
Frequency Stability over the Operating Temperature (ref. to $+25^{\circ}\text{C}$)	-15		+15	ppm	See options
Equivalent series resistance "R1" (over -40°C to $+125^{\circ}\text{C}$)		< 100	200	Ω	10.0000 – 11.9999MHz
		< 60	100		12.0000 – 15.9999MHz
		< 40	70		16.0000 – 19.9999MHz
		< 25	50		20.0000 – 29.9999MHz
		< 20	40		30.0000 – 39.9999MHz
		< 18	40		40.0000 – 54.0000MHz
Shunt Capacitance (C0)		< 1.2	2.0	pF	
Load Capacitance (CL)		4.0		pF	See options
Drive Level		10	100	μW	
Aging (1 year)	-2		+2	ppm	@ $25^{\circ}\text{C} \pm 3^{\circ}\text{C}$
Insulation Resistance	500			M Ω	@ 100Vdc $\pm 15\text{V}$

Part Identification [\[Note 1\]](#)



Note 1: Contact Abracon for part number requests with carrier frequency callouts up to 5 & 6 digit accuracy after the decimal.

Mechanical Dimensions



Dimensions: inches [mm]

Reflow Profile [JEDEC J-STD-020]

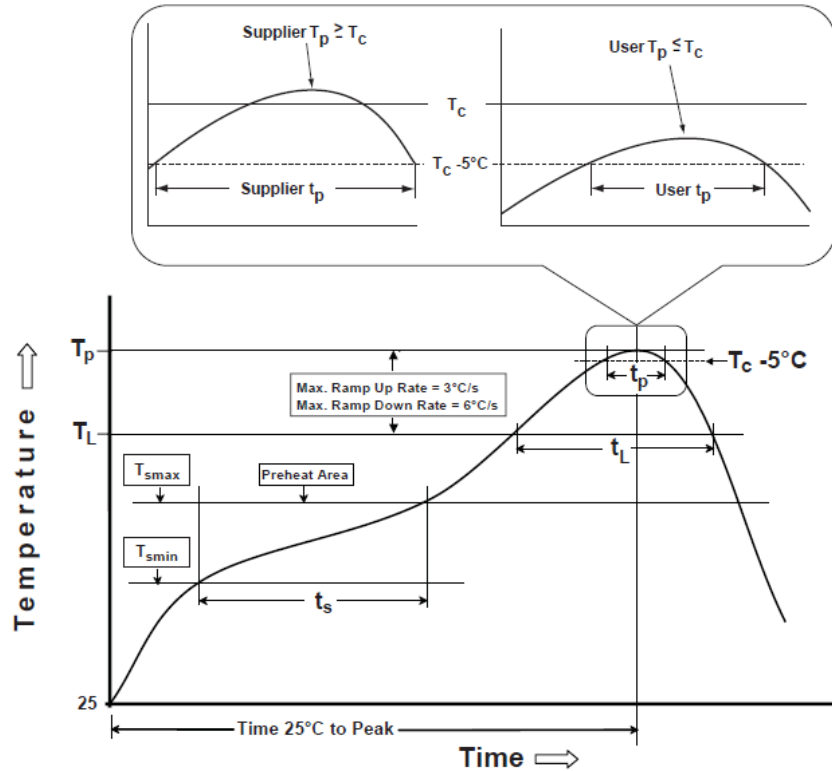


Table 1

SnPb Eutectic Process
Classification Temperatures (T_C)

Package Thickness	Volume mm ³ <350	Volume mm ³ ≥350
<2.5 mm	235 °C	220 °C
≥2.5 mm	220 °C	220 °C

Table 2

Pb-Free Process
Classification Temperatures (T_C)

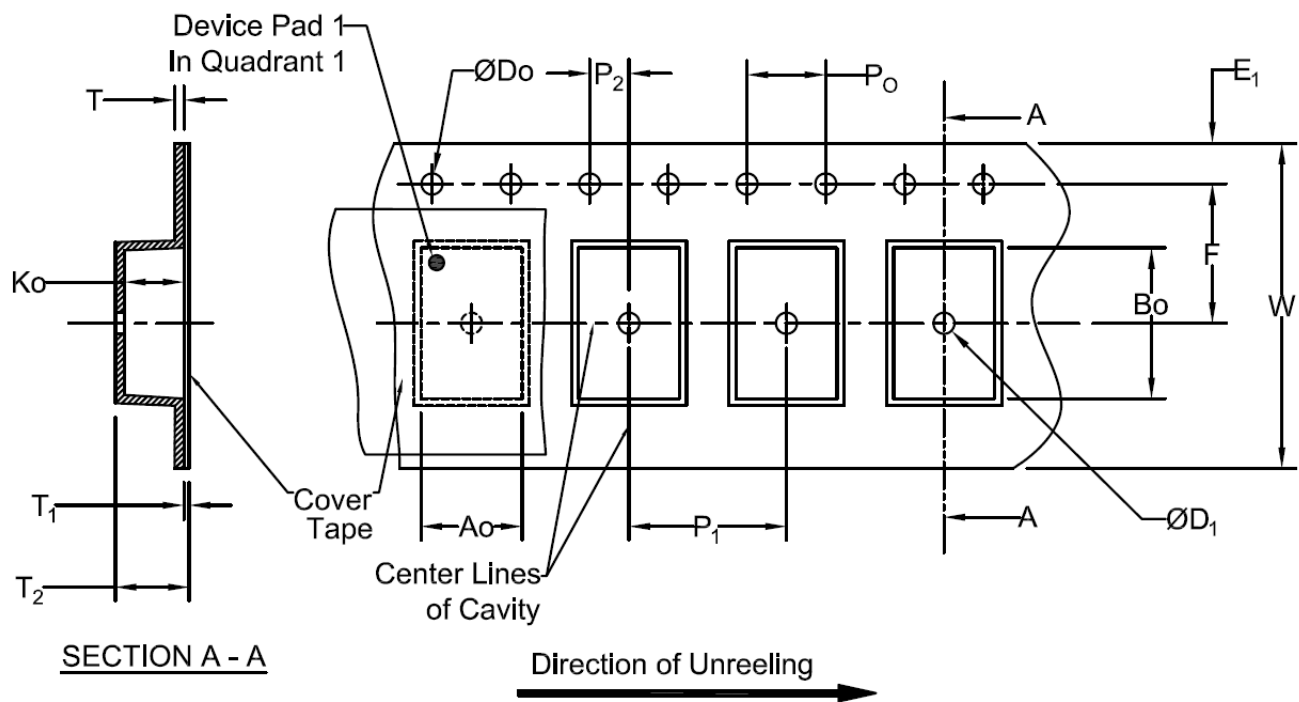
Package Thickness	Volume mm ³ <350	Volume mm ³ 350-2000	Volume mm ³ >2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 mm - 2.5 mm	260 °C	250 °C	245 °C
>2.5 mm	250 °C	245 °C	245 °C

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Preheat / soak		
Temperature minimum (T_{smin})	100°C	150°C
Temperature maximum (T_{smax})	150°C	200°C
Time (T_{smin} to T_{smax}) (t_s)	60 - 120 sec.	60 - 120 sec.
Average ramp-up rate (T_{smax} to T_p)	3°C/sec. max	3°C/sec. max
Liquidous temperature (T_L)	183°C	217°C
Time at liquidous (t_L)	60 - 150 sec.	60 - 150 sec.
Peak package body temperature (T_p)*	see Table 1	see Table 2
Time (t_p)** within 5°C of the specified classification temperature (T_C)	20 sec.	30 sec.
Ramp-down rate (T_p to T_{smax})	6°C/sec. max	6°C/sec. max
Time 25°C to peak temperature	6 min. max	8 min. max
Reflow cycles	2 max	2 max

*Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum.

**Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.

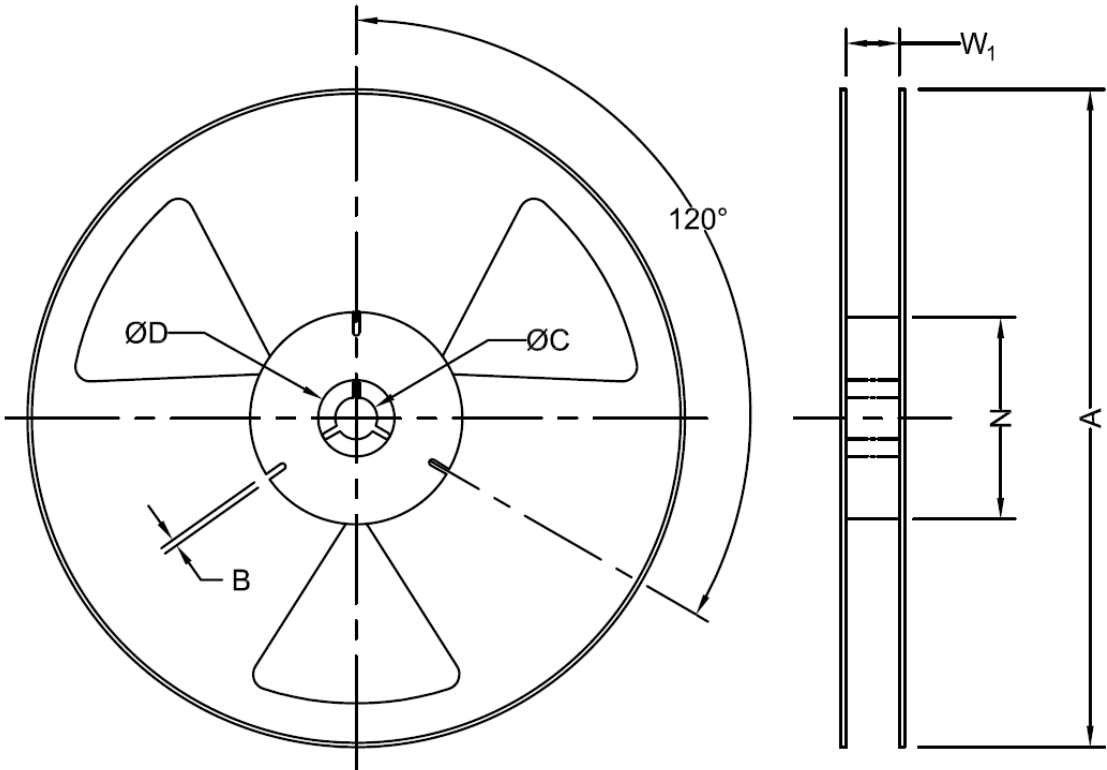
Packaging



Tape Specifications (mm)							
Width	Ao	Bo	Do	D ₁	E ₁	F	Ko
8mm	*	*	1.5+0.1/-0.0	1.0	1.75±0.1	3.5±0.05	*
Width	P ₁	P ₂	P ₀	T (Max)	T ₁ (Max)	T ₂ (Max)	W (Max)
8mm	4.0±0.1	2.0±0.05	4.0±0.1	0.6	0.1	2.5	8.3

*Note: Compliant to EIA-481

Packaging continued



Reel Specifications (mm)							
Width	Qty/Reel	A (Nom)	B (Min)	C (Min)	D (Min)	N (Min)	*W ₁
8mm	3000	178	1.5	13.0+0.5/-0.2	20.2	50	8.4+1.5/-0.0

*Note: Measured at Hub